



PATENT

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1/2/02**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: O'DONNELL

Attorney Docket No.:
LAM1P133/P0582

Application No.: 09/472,757

Examiner: Umez Eronini, L.

Filed: December 27, 1999

Group: 1765

Title: INSITU POST ETCH PROCESS TO
REMOVE REMAINING PHOTORESIST AND
RESIDUAL SIDEWALL PASSIVATION**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail to: Box Non-Fee Amendment, Commissioner for Patents, Washington, D.C. 20231 on November 27, 2001.

Signed: _____


Sue Funchess**AMENDMENT A**Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

Dear Sir or Madame:

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DEC 31 2001
TC 1700

This is in response to the office action mailed August 29, 2001. The period of response extends to November 29, 2001. Please consider the following remarks and amend the above-identified patent application as follows.

In The Claims:

Please add claims 17-18 as follows:

Sub 17. (New) The method, as recited in claim 1, wherein the stripping away comprises removing parts of the metal-containing layer that are redeposited to form residual sidewall passivation.

A1 18. (New) The method, as recited in claim 1, wherein the stripping away comprises accelerating oxygen plasma to the substrate to remove parts of the metal-containing layer that are redeposited to form residual sidewall passivation.